

In the Claims:

Please add the following new claims:

Rule 1.26 ⁵²
~~52.~~ (New) A substrate capable of use in an optical system, comprising a thermosetting plastic, wherein the thermosetting plastic comprises a material selected from the group consisting of polycyanurate resins, polycyanate resins, and mixtures of polycyanurate resins and polycyanate resins.

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~~53.~~ (New) The substrate according to claim 52, wherein the thermosetting plastic further comprises at least one of epoxy resins, bismaleimide resins, or bismaleimide triazine resins.

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~~54.~~ (New) The substrate according to claim 52, wherein the thermosetting plastic has a glass transition temperature of not less than 150°C.

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~~55.~~ (New) The substrate according to claim 54, wherein the thermosetting plastic has a glass transition temperature of not less than 200°C.

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~~56.~~ (New) The substrate according to claim 55, wherein the thermosetting plastic has a glass transition temperature of not less than 250°C.

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~~57.~~ (New) The substrate according to claim 56, wherein the thermosetting plastic has a glass transition temperature of not less than 300°C.

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~~58.~~ (New) The substrate according to claim 52, wherein the substrate additionally comprises a thermoplastic material and/or an elastomeric material.

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~~59.~~ (New) The substrate according to claim 58, wherein the elastomeric material is selected from the group consisting of acrylonitrile-butadiene, acrylonitrile-butadiene-styrene, polyesters and polyurethanes.

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~~60.~~ (New) The substrate according to claim 58, wherein the thermoplastic material is selected from the group consisting of polyimides, polyetherimides,

polyethersulfones, polysulfones, polyarylates, polycarbonates, polyesters, and mixtures thereof.

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61. (New) The substrate according to claim 52, wherein the substrate additionally comprises at least one material having a thermal conductivity that is higher than the thermal conductivity of said thermosetting plastic.

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62. (New) The substrate according to claim 61, wherein the material having a higher thermal conductivity than said thermosetting plastic is selected from the group consisting of metals, alloys, carbon black, and graphite.

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63. (New) The substrate according to claim 62, wherein the material having a higher thermal conductivity than said thermosetting plastic is selected from the group consisting of silver, copper, and mixtures of silver and copper.

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64. (New) The substrate according to claim 61, wherein the material having a higher thermal conductivity is incorporated into the thermosetting plastic in the form of a powder, a granulate, of flakes or of woven or non-woven textiles.

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65. (New) The substrate according to claim 61, wherein the substrate includes restricted areas wherein the material having a higher thermal conductivity is only incorporated into the thermosetting plastic in restricted areas of the substrate.

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66. (New) The substrate according to claim 52, wherein the substrate additionally comprises at least one material which is capable of lowering the coefficient of thermal expansion of the thermosetting plastic.

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67. (New) The substrate according to claim 66, wherein the material which lowers the coefficient of thermal expansion of the thermosetting plastic is selected from the group consisting of glass, ceramics, metal, graphite and carbon black.